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PATENT #11/c
Ser. No. 09/581,663
Atty. Docket No. 10191/1466
10/23/02
RESPONSE UNDER 37 C.F.R. 1.116
-EXPEDITED PROCEDURE -
EXAMINING GROUP 1746

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Volker BECKER *et al.*
Serial No. : 09/581,663
Filed : August 3, 2000
For : METHOD FOR PROCESSING SILICON
BY ETCHING PROCESSES
Group Art Unit : 1765
Examiner : S. AHMED
Confirmation No. : 4295

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Date: October 7, 2002

Reg. No. 36,197

Signature: _____

Jong H. Lee

AMENDMENT UNDER 37 C.F.R. § 1.116

Sir:

In response to the Final Office Action mailed July 5, 2002, the Applicants respectfully submit the following amendments and remarks. The Applicants respectfully assert that the Requested Amendments shown below should be entered because they place the application in condition for allowance and do not raise new issues.

REQUESTED AMENDMENTS

IN THE CLAIMS:

Please amend the claims as follows:

33. (Once Amended) A method for etching a silicon layered body, which has a first silicon layer (15) that is provided with an etching mask (10) for defining lateral recesses (21); work with a